COLLOIDAL SILICA CHEMICAL-MECHANICAL POLISHING COMPOSITION

ABSTRACT OF THE DISCLOSURE

A chemical-mechanical polishing composition includes colloidal silica abrasive particles dispersed in a liquid carrier. The colloidal silica abrasive particles include a nitrogen-containing or phosphorus-containing compound incorporated therein such that the particles have a positive charge. The composition may be used to polish a substrate including a silicon oxygen material such as TEOS.

Fig. 1